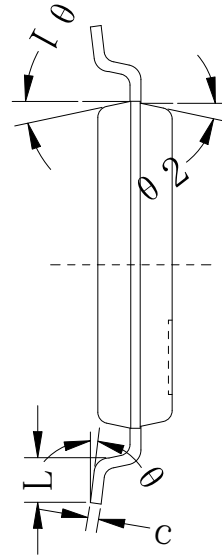
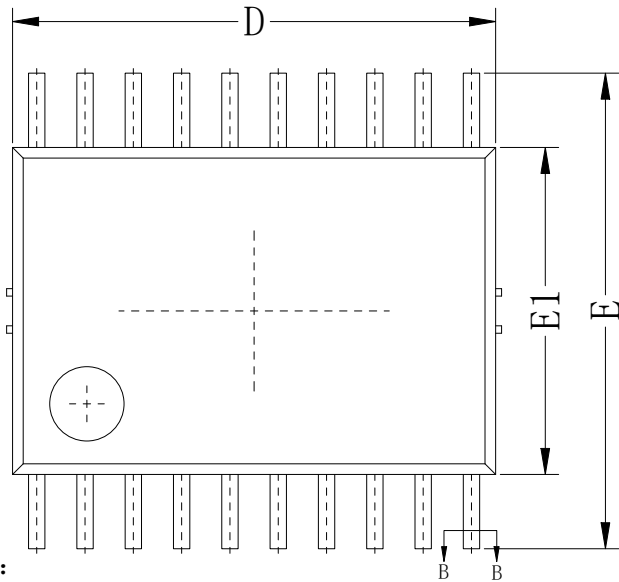
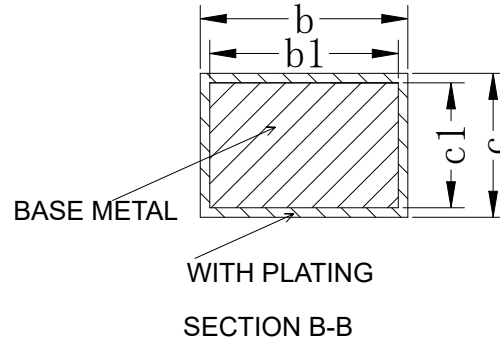
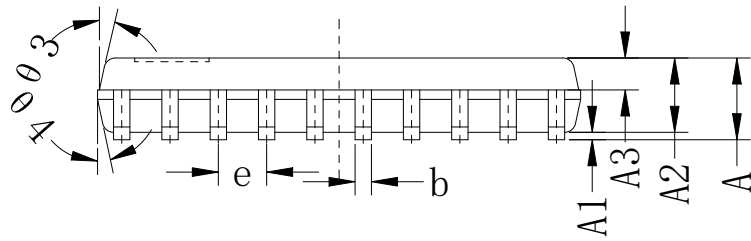




MARK		REVISION RECORD	VERSION	REVISERE
①	修改管脚		B	
②	1、更正视图方向；2、更正PIN1标识形状		C	



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.20
A1	0.05	0.10	0.15
A2	0.80	1.00	1.05
A3	0.38	0.43	0.48
b	0.17	--	0.27
b1	0.16	0.22	0.26
c	0.13	--	0.15
c1	0.12	0.13	0.14
D	6.40	6.50	6.60
E	6.25	6.40	6.55
E1	4.30	4.40	4.50
e	0.65 (BSC)		
L	0.45	0.60	0.75
θ	0°	~	8°
θ 1	10°	~	14°
θ 2	10°	~	14°
θ 3	10°	~	14°
θ 4	10°	~	14°

技术说明:

- LEADFRAME MATERIAL: COPPER;  
引线框架材料: 铜;
- LEADFRAME THICKNESS: 0.127mm;  
引线框架厚度: 0.127mm;
- BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;  
塑封体长度及宽度尺寸不包括塑封溢胶;
- REFERENCE: JEDEC MS-013, MS-012. 参考标准: JEDEC MS-013, MS-012.

SCALE	UNIT	mm	TITLE
DATE	2024-11-20		TSSOP20L 产品成型图
DESIGNER	CHECKER	APPROVER	
张金萍			DWG.NO. MT-PD-090
2024-11-20			VERSION C 第1页, 共1页